

Serial Nr.: 09/209,634  
Art Unit: 2811

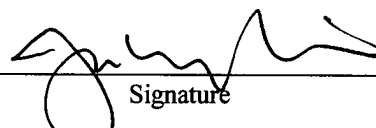
GAU 2811  
UPA-98165

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/209,634 Examiner: Luan Thai  
Inventor: Fang-Jun Leu, Rong-Shen Lee, Hsin-Chien Huang,  
Randy Hsiao-Yu Lo and Chiang-Han Day  
Filed: December 10, 1998 Art Unit: 2811  
Title: Flip-Chip Ball Grid Array Package With A Heat Slug

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Signature

July 19, 2000  
Date

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

AMENDMENT

In response to the Office Action mailed 05/03/2000, please amend the above-identified application as follows:

DRAWINGS:

FIG. 1 is designated by a legend --Prior Art-- as marked in red in the attached drawing.

SPECIFICATION:

Page 5, line 19, before "The good", insert the sentence, The hollow cylindrical structure  
provides good support and protection for the semiconductor package to prevent it  
from being damaged by an external force.

Page 5, line 20, change "assist" to --assists--.



#3/assn  
Corr  
Chen  
7/27/00  
enter phone  
LT.

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